



QNHCHIP

QNM7611AJ

# Product Specification

**QNM7611AJ**

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30V Complementary MOSFET



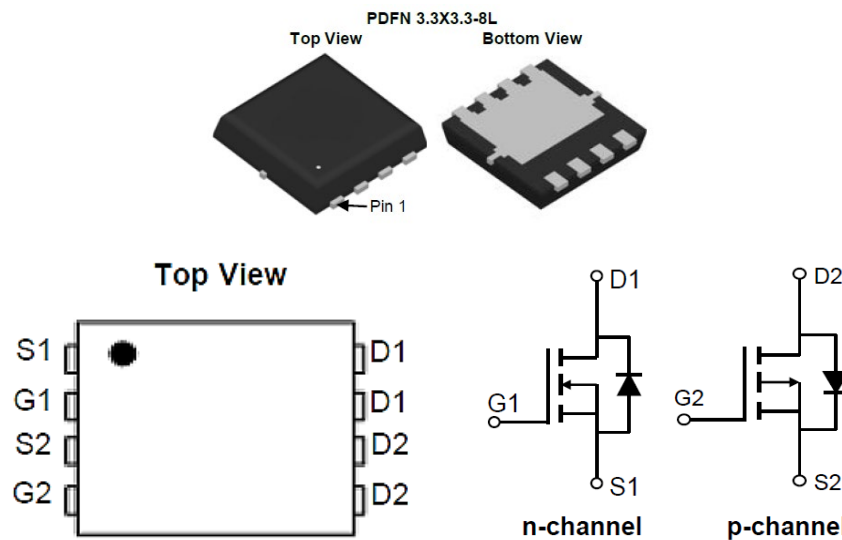
## FEATURES

- N-Channel: 30V, 10A  
 $R_{DS(ON)}$  Typ= 14m $\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(ON)}$  Typ= 22m $\Omega$  @  $V_{GS} = 4.5V$
- P-Channel: -30V, -7A  
 $R_{DS(ON)}$  Typ= 34m $\Omega$  @  $V_{GS} = -10V$   
 $R_{DS(ON)}$  Typ= 46m $\Omega$  @  $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge

## Applications

- Battery Protection
- Load Switch
- Power Management

## Pin Description



NO.	Symbol	Description
1	S1	SOURCE
2	G1	GATE
3	S2	SOURCE
4	G2	GATE
5	D1	DRAIN
6	D1	DRAIN
7	D2	DRAIN
8	D2	DRAIN



## Absolute Maximum Ratings

(@  $T_C = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	N-Channel Value	P-Channel Value	Units
$V_{DS}$	Drain-to-Source Voltage	30	-30	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	-7	A
		$T_C = 100^\circ\text{C}$	-5	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	48	-40	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	12	20	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	6.9	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	21	18	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150		$^\circ\text{C}$



## N-Channel Electrical Characteristics

(T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250uA, V <sub>GS</sub> = 0V	30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	-	-	1.0	uA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	1.0	1.7	2.5	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3A	-	14	27	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 2A	-	22	44	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 15V, f = 1MHz	-	511	-	pF
C <sub>oss</sub>	Output Capacitance		-	66	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	52	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 10V V <sub>DS</sub> = 15V, I <sub>D</sub> = 3A	-	10	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	2	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	2	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 15V I <sub>D</sub> = 3A, R <sub>GEN</sub> = 3 Ω	-	4	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	6	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	12	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	3	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	10	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	48	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 5A	-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> = 3A, di/dt = 100A/us	-	8	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	2	-	nC



## P-Channel Electrical Characteristics

(T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = -250uA, V <sub>GS</sub> = 0V	-30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V	-	-	-1.0	uA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250uA	-1.0	-1.7	-2.5	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -5A	-	34	48	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -3A	-	46	67	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = -15V, f = 1MHz	-	516	-	pF
C <sub>oss</sub>	Output Capacitance		-	71	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	60	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to -10V V <sub>DS</sub> = -15V, I <sub>D</sub> = -3A	-	16	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	3	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	3	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = -10V, V <sub>DD</sub> = -15V I <sub>D</sub> = -3A, R <sub>GEN</sub> = 3 Ω	-	4	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	2	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	38	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	22	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	-7	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-40	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = -5A	-	-	-1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> = -3A, di/dt = 100A/us	-	10	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	3	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. E<sub>AS</sub> condition: Starting T<sub>J</sub>=25°C, V<sub>DD</sub>=20V, V<sub>G</sub>=10V, R<sub>G</sub>=25ohm, L=0.5mH, I<sub>AS</sub>=7A

E<sub>AS</sub> condition: Starting T<sub>J</sub>=25°C, V<sub>DD</sub>=-20V, V<sub>G</sub>=-10V, R<sub>G</sub>=25ohm, L=0.5mH, I<sub>AS</sub>=-9A

3. Pulse Test: Pulse Width ≤ 300us, Duty Cycle ≤ 0.5%.



### Test Circuit N-MOS

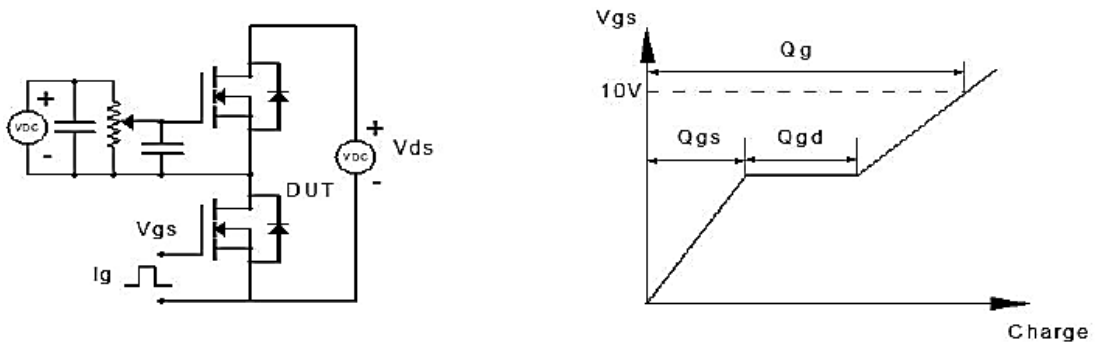


Figure 1: Gate Charge Test Circuit & Waveform

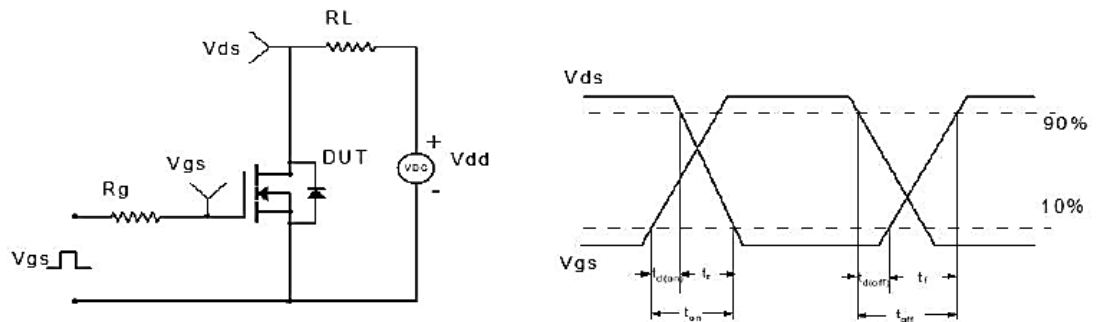


Figure 2: Resistive Switching Test Circuit & Waveform

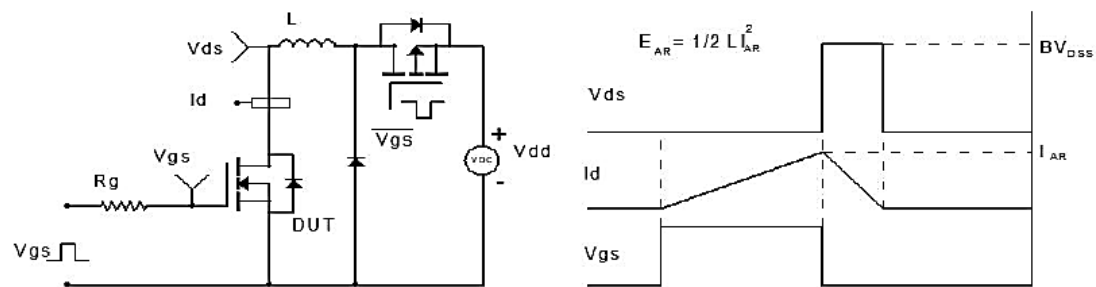


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

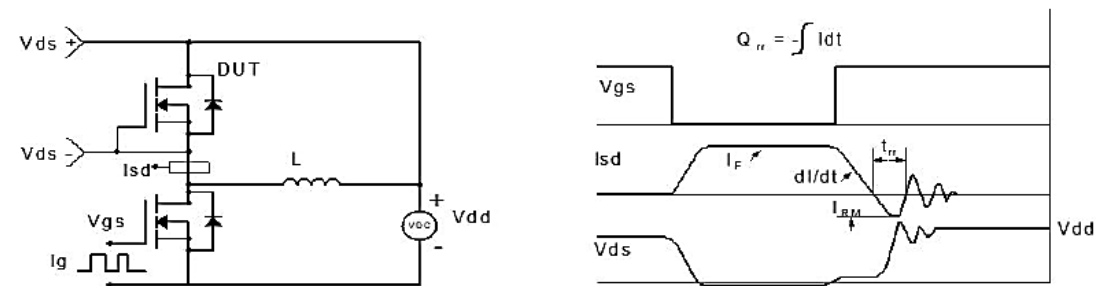


Figure 4: Diode Recovery Test Circuit & Waveform



### Test Circuit P-MOS

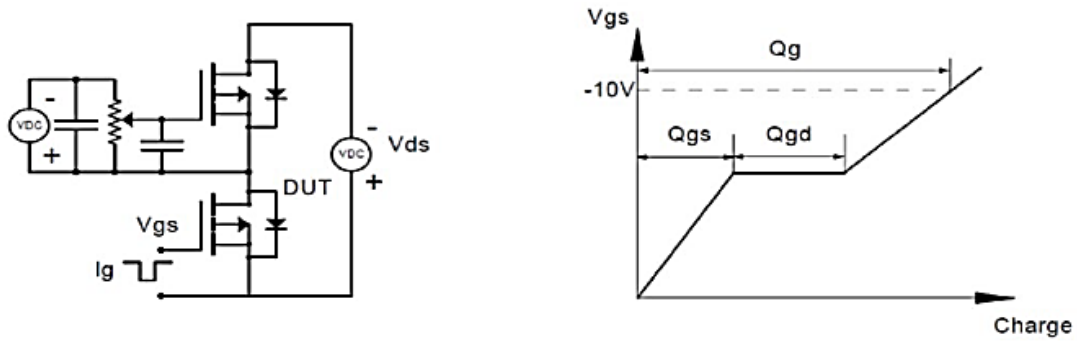


Figure 1: Gate Charge Test Circuit & Waveform

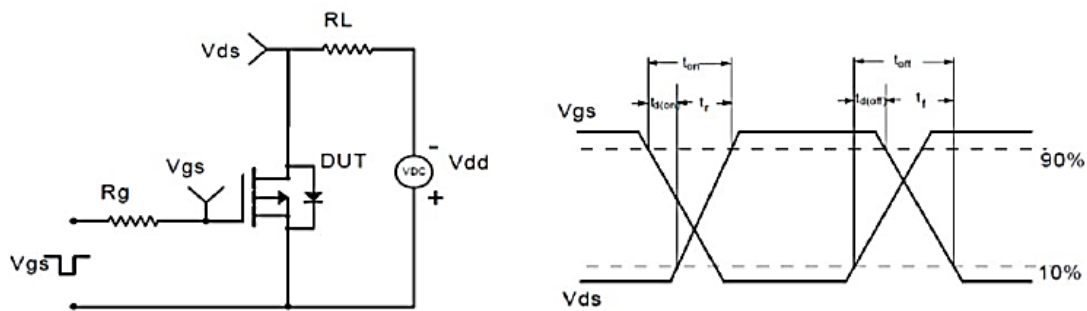


Figure 2: Resistive Switching Test Circuit & Waveform

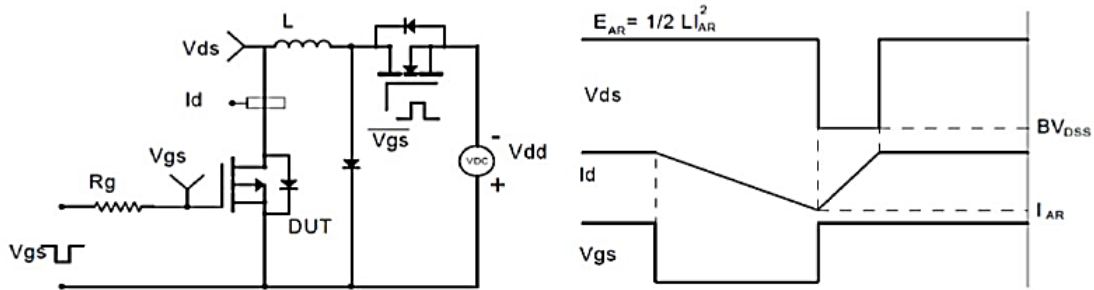


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

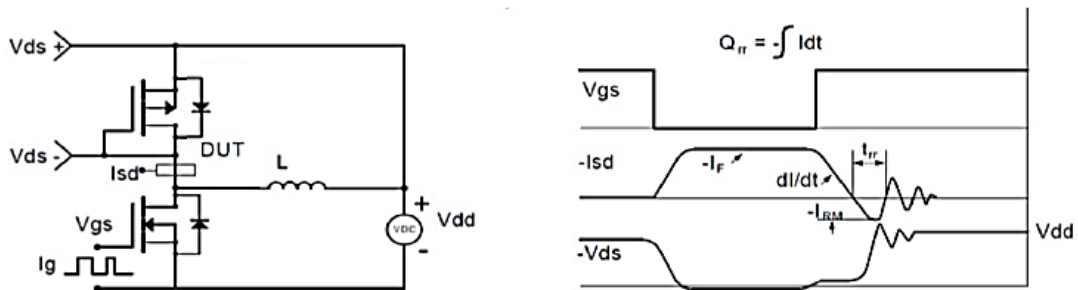
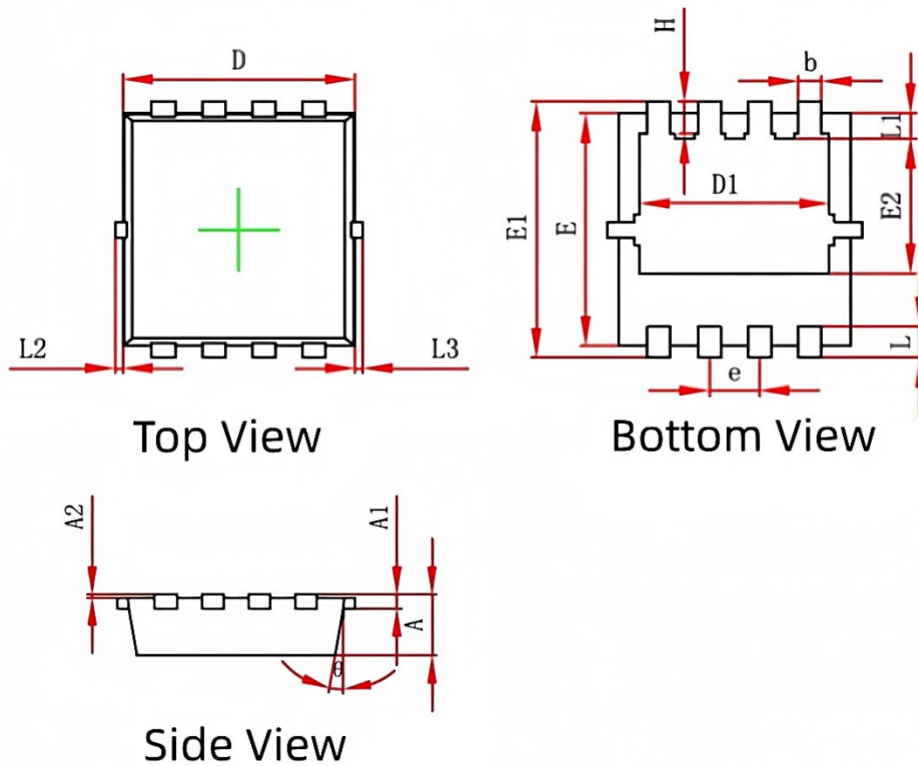


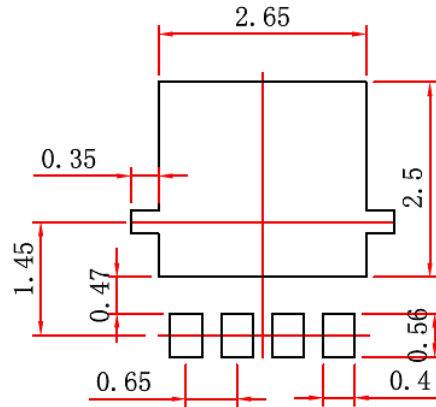
Figure 4: Diode Recovery Test Circuit & Waveform



## Package Mechanical Data(PDFN 3.3x3.3-8)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
$\theta$	9°	13°	9°	13°



Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05\text{mm}$ .
3. The pad layout is for reference purposes only.

## Ordering information

Order Code	Package	$V_{DS}(V)$	$I_D(A)$	$R_{DS(ON)}(m\Omega)$	
				$V_{GS}=10V$	$V_{GS}=4.5V$
QNM7611AJ	PDFN 3.3x3.3-8	30	10	$V_{GS}=10V$	14
				$V_{GS}=4.5V$	22
		-30	-7	$V_{GS}=-10V$	34
				$V_{GS}=-4.5V$	46